

Drahtleiter - family

wire conductor - family

WO 97/30418

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country

AU	Australien
CA	Canada
CN	China
JP	Japan
KR	Republik Korea
US	Vereinigte Staaten von Amerika

EP 0880754

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country

AT	Österreich
CH	Schweiz
DE	Deutschland
ES	Spanien
FR	Frankreich
GB	Großbritannien
IE	Irland
IT	Italien
LI	Lichtenstein
NL	Niederlande

(57) Abstract

The invention relates to a method and device for bonding a wire conductor (13) when producing a transponder unit having a wirewound coil (12) and a chip unit (15) and arranged on a substrate (11). During a first phase the wire conductor (13) extends across the bonding pad (18,19) or a region receiving the bonding pad, and is fixed to the substrate (11) in relation to the bonding pad (18,19) or the region associated with the bonding pad, and during a second phase the wire connector (13) is connected to the bonding pad (18,19) by connection means (25,37).

